

Amendments to the Claims:

The following listing of claims will replace all prior versions, and listings, of claims in the application:

- D1
1. (Currently Amended) A flexible interconnect substrate comprising:
a tape-shaped base substrate; and
an interconnect pattern formed on the base substrate,
wherein the base substrate includes:
a first region in which a portion of the interconnect pattern has been formed
and which will form a unit when separated from the base substrate; and
a second region positioned next to the first region in the longitudinal direction
of the base substrate; and
wherein the second region has low-bending-resistance portions which are
formed asymmetrically in regions ~~regions~~, that exclude and sandwich a central portion of the
second region in the widthwise direction of the base substrate, on either side with respect to
the central portion for ensuring that the second region bends more readily in the direction in
which the longitudinal axis of the base substrate bends, in comparison with the first region,
wherein the whole portion of the interconnect pattern in the first region
extends across the widthwise direction of the base substrate.
 2. (Previously Presented) The flexible interconnect substrate as defined in
claim 1,
wherein each of the low-bending-resistance portions is one of through-holes,
cuts, and a thinner portion.
 3. (Previously Presented) The flexible interconnect substrate as defined in
claim 1,

D1 wherein a high-bending-resistance portion is formed in each of the first region and the central portion of the second region in the widthwise direction of the base substrate;

wherein the high-bending-resistance portion is formed to avoid regions that exclude the central portion of the second region in the widthwise direction of the base substrate; and

wherein the regions avoided by the high-bending-resistance portion relatively form the low-bending-resistance portions.

4. (Original) The flexible interconnect substrate as defined in claim 1, wherein a hole is formed in the first region of the base substrate; and wherein a portion of the interconnect pattern is positioned within the hole.

5. (Original) The flexible interconnect substrate as defined in claim 4, wherein the second region is formed to bend more readily than the first region that bends readily due to the formation of the hole.

6. (Previously Presented) The flexible interconnect substrate as defined in claim 1,

wherein the low-bending-resistance portions are formed in a straight line within the second region, across the width of the base substrate.

7. (Previously Presented) The flexible interconnect substrate as defined in claim 6,

wherein the low-bending-resistance portions are disposed on two edge portion sides of the base substrate, symmetrically with respect to the center in the widthwise direction of the base substrate.

8. (Withdrawn) The flexible interconnect substrate as defined in claim 6,

① wherein the low-bending-resistance portions are disposed on two edge portion sides of the base substrate, asymmetrically with respect to the center in the widthwise direction of the base substrate.

9. (Withdrawn) The flexible interconnect substrate as defined in claim 8, wherein the interconnect pattern is formed to be offset towards either of two edge portions of the base substrate, with respect to the center in the widthwise direction of the base substrate.

10. (Original) A tape-shaped semiconductor device comprising:
the flexible interconnect substrate as defined in claim 1; and
a semiconductor chip connected electrically to the interconnect pattern of the base substrate.

11. (Withdrawn) A tape-shaped semiconductor device comprising:
the flexible interconnect substrate as defined in claim 8; and
a semiconductor chip which is disposed offset towards either of two edge portions of the base substrate, with respect to the center thereof in the widthwise direction of the base substrate, and which is connected electrically to the interconnect pattern of the base substrate.

12. (Withdrawn) A tape-shaped semiconductor device comprising:
the flexible interconnect substrate as defined in claim 9; and
a semiconductor chip which is disposed offset towards either of two edge portions of the base substrate, with respect to the center thereof in the widthwise direction of the base substrate, and which is connected electrically to the interconnect pattern of the base substrate.

13-21. (Canceled).

D¹ 22. (Previously Presented) A method of manufacturing a semiconductor device, comprising the steps of:

winding the flexible interconnect substrate as defined in claim 1 onto a reel in preparation; and then

pulling the flexible interconnect substrate out from the reel.

23. (Previously Presented) A method of manufacturing a semiconductor device, comprising the steps of:

winding a tape-shaped semiconductor device which comprises the flexible interconnect substrate as defined in claim 1 and a semiconductor chip connected electrically to the interconnect pattern of the flexible interconnect substrate, onto a reel in preparation; and then

pulling the tape-shaped semiconductor device out from the reel.

24. (Original) The method of manufacturing a semiconductor device as defined in claim 23,

wherein the flexible interconnect substrate is punched out at the first region, during the step of pulling the tape-shaped semiconductor device out from the reel.
